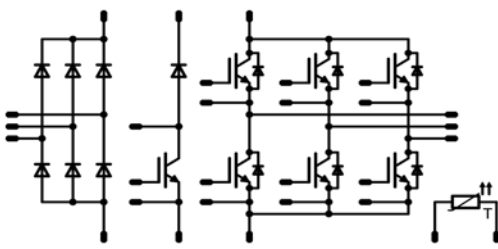


MiniSKiiP® 3 PIM		1200V / 50A	
Features - Solderless interconnection - Trench Fieldstop IGBT4 technology		MiniSKiiP® 3 housing 	
Target Applications Industrial Drives 		Schematic 	
Types V23990-K428-A40-PM			

Maximum Ratings

$T_j=25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Input Rectifier Diode				
Repetitive peak reverse voltage	V_{RRM}		1600	V
DC forward current	I_{FAV}	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	50	A
Surge forward current	I_{FSM}	$t_p=10\text{ms}$ $T_j=25^{\circ}\text{C}$	450	A
I^2t -value	I^2t		1020	A^2s
Power dissipation per Diode	P_{tot}	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	62	W
Maximum Junction Temperature	T_{jmax}		150	$^{\circ}\text{C}$
Inverter Transistor				
Collector-emitter break down voltage	V_{CE}		1200	V
DC collector current	I_C	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	40	A
Repetitive peak collector current	I_{Cpulse}	t_p limited by T_{jmax}	150	A
Power dissipation per IGBT	P_{tot}	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	88	W
Gate-emitter peak voltage	V_{GE}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_j=150^{\circ}\text{C}$ $V_{GE}=15\text{V}$	10 800	μs V
Maximum Junction Temperature	T_{jmax}		175	$^{\circ}\text{C}$

Maximum Ratings

 $T_j=25^{\circ}\text{C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
-----------	--------	-----------	-------	------

Inverter Diode

Repetitive peak reverse voltage	V_{RRM}		1200	V
DC forward current	I_F	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	35	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	335	A
Power dissipation per Diode	P_{tot}	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	66	W
Maximum Junction Temperature	T_{jmax}		175	$^{\circ}\text{C}$

Brake Transistor

Collector-emitter break down voltage	V_{CE}		1200	V
DC collector current	I_C	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	45	A
Repetitive peak collector current	I_{Cpuls}	t_p limited by T_{jmax}	150	A
Power dissipation per IGBT	P_{tot}	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	101	W
Gate-emitter peak voltage	V_{GE}		± 20	V
Short circuit ratings	t_{SC} V_{CC}	$T_j=150^{\circ}\text{C}$ $V_{GE}=15\text{V}$	10 800	μs V
Maximum Junction Temperature	T_{jmax}		175	$^{\circ}\text{C}$

Brake Diode

Repetitive peak reverse voltage	V_{RRM}		1200	V
DC forward current	I_F	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	38	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	335	A
Power dissipation per Diode	P_{tot}	$T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$	70	W
Maximum Junction Temperature	T_{jmax}		175	$^{\circ}\text{C}$

Thermal Properties

Storage temperature	T_{stg}		$-40\dots+125$	$^{\circ}\text{C}$
Operation temperature under switching condition	T_{op}		$-40\dots+(T_{jmax} - 25)$	$^{\circ}\text{C}$

Insulation Properties

Insulation voltage	V_{is}	$t=2\text{s}$ DC voltage	4000	V
Creepage distance			min 12.7	mm
Clearance			min 12.7	mm

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V _{GE} [V] or V _{GS} [V]	V _r [V] or V _{CE} [V] or V _{DS} [V]	I _c [A] or I _F [A] or I _D [A]	T _J	Min	Typ	Max	
Input Rectifier Diode										
Forward voltage	V _F				35	T _J =25°C T _J =125°C	0,8	1,03 0,93	1,35	V
Threshold voltage (for power loss calc. only)	V _{to}					T _J =25°C T _J =125°C		0,9 0,74		V
Slope resistance (for power loss calc. only)	r _t					T _J =25°C T _J =125°C		0,004 0,006		Ω
Reverse current	I _r			1500		T _J =25°C T _J =125°C			0,1 1,1	mA
Thermal resistance chip to heatsink per chip	R _{thJH}	Thermal grease thickness≤50µm λ=1W/mK						1,14		K/W
Thermal resistance chip to case per chip	R _{thJC}							N/A		
Inverter Transistor										
Gate emitter threshold voltage	V _{GE(th)}	V _{CE} =V _{GE}			0,0017	T _J =25°C T _J =150°C	5	5,8	6,5	V
Collector-emitter saturation voltage	V _{CE(sat)}		15		50	T _J =25°C T _J =150°C	1,6	1,91 2,39	2,4	V
Collector-emitter cut-off current incl. Diode	I _{CES}			1200		T _J =25°C T _J =150°C			0,06	mA
Gate-emitter leakage current	I _{GES}		20	0		T _J =25°C T _J =150°C			600	nA
Integrated Gate resistor	R _{gint}							4		Ω
Turn-on delay time	t _{d(on)}	R _{goff} =8Ω R _{gon} =8Ω	±15	600	50	T _J =25°C T _J =150°C		106 111		ns
Rise time	t _r					T _J =25°C T _J =150°C		18 25		
Turn-off delay time	t _{d(off)}					T _J =25°C T _J =150°C		228 298		
Fall time	t _f					T _J =25°C T _J =150°C		84 125		
Turn-on energy loss per pulse	E _{on}					T _J =25°C T _J =150°C		2,66 4,46		mWs
Turn-off energy loss per pulse	E _{off}					T _J =25°C T _J =150°C		2,78 4,58		
Input capacitance	C _{ies}	f=1MHz	0	25		T _J =25°C		2770		pF
Output capacitance	C _{oss}							205		
Reverse transfer capacitance	C _{rss}							160		
Gate charge	Q _{Gate}		±15			T _J =25°C		380		nC
Thermal resistance chip to heatsink per chip	R _{thJH}	Thermal grease thickness≤50µm λ=1W/mK						1,09		K/W
Thermal resistance chip to case per chip	R _{thJC}							N/A		
Inverter Diode										
Diode forward voltage	V _F				50	T _J =25°C T _J =150°C	1,5	2,19 2,21	2,9	V
Peak reverse recovery current	I _{RRM}	R _{gon} =8Ω	±15	600	50	T _J =25°C T _J =150°C		61,3 70,7		A
Reverse recovery time	t _{rr}					T _J =25°C T _J =150°C		144 312		ns
Reverse recovered charge	Q _{rr}					T _J =25°C T _J =150°C		3,74 8,8		µC
Peak rate of fall of recovery current	di(rec)max /dt					T _J =25°C T _J =150°C		3494 950		A/µs
Reverse recovered energy	E _{rec}					T _J =25°C T _J =150°C		1,38 3,48		mWs
Thermal resistance chip to heatsink per chip	R _{thJH}					Thermal grease thickness≤50µm λ=1W/mK				
Thermal resistance chip to case per chip	R _{thJC}							N/A		

Characteristic Values

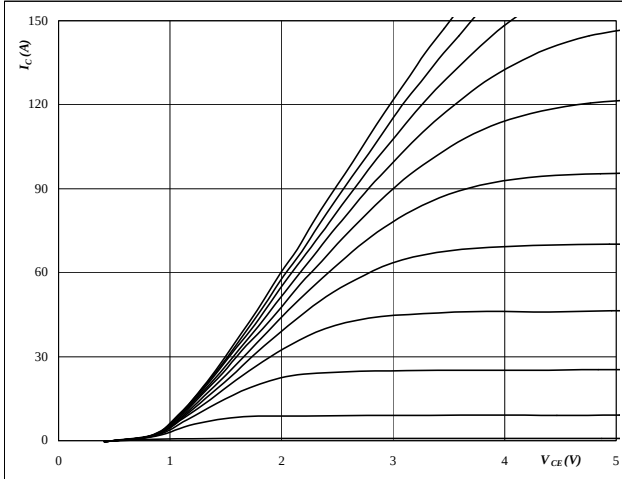
Parameter	Symbol	Conditions					Value			Unit
			V _{GE} [V] or V _{GS} [V]	V _r [V] or V _{CE} [V] or V _{DS} [V]	I _c [A] or I _F [A] or I _b [A]	T _J	Min	Typ	Max	
Brake Transistor										
Gate emitter threshold voltage	V _{GE(th)}	V _{CE} =V _{GE}			0,0017	T _J =25°C T _J =150°C	5	5,8	6,5	V
Collector-emitter saturation voltage	V _{CE(sat)}		15		50	T _J =25°C T _J =150°C	1,6	1,85 2,28	2,4	V
Collector-emitter cut-off incl diode	I _{CES}			1200		T _J =25°C T _J =150°C			0,06	mA
Gate-emitter leakage current	I _{GES}		20	0		T _J =25°C T _J =150°C			600	nA
Integrated Gate resistor	R _{gint}							4		Ω
Turn-on delay time	t _{d(on)}	Rgoff=8Ω Rgon=8Ω	±15	600	50	T _J =25°C T _J =150°C		105 111		ns
Rise time	t _r					T _J =25°C T _J =150°C		18 31		
Turn-off delay time	t _{d(off)}					T _J =25°C T _J =150°C		223 295		
Fall time	t _f					T _J =25°C T _J =150°C		87 132		
Turn-on energy loss per pulse	E _{on}					T _J =25°C T _J =150°C		2,63 5,57		mWs
Turn-off energy loss per pulse	E _{off}	T _J =25°C T _J =150°C		2,68 4,59						
Input capacitance	C _{ies}	f=1MHz	0	25		T _J =25°C		2770		pF
Output capacitance	C _{oss}							205		
Reverse transfer capacitance	C _{rss}							160		
Gate charge	Q _{Gate}		±15			T _J =25°C		380		nC
Thermal resistance chip to heatsink per chip	R _{thJH}	Thermal grease thickness≤50µm						0,94		K/W
Thermal resistance chip to case per chip	R _{thJC}	λ=1W/mK						N/A		
Brake Diode										
Diode forward voltage	V _F				50	T _J =25°C T _J =150°C	1,5	2,12 2,1	2,9	V
Reverse leakage current	I _r			1200		T _J =25°C T _J =150°C			60 5100	µA
Peak reverse recovery current	I _{RRM}	Rgon=8Ω	±15	600	50	T _J =25°C T _J =150°C		60,6 40,3		A
Reverse recovery time	t _{rr}					T _J =25°C T _J =150°C		145 560		ns
Reverse recovered charge	Q _{rr}					T _J =25°C T _J =150°C		3,61 8,54		µC
Peak rate of fall of recovery current	di(rec)max /dt					T _J =25°C T _J =150°C		3649 154		A/µs
Reverse recovery energy	E _{rec}					T _J =25°C T _J =150°C		1,31 3,32		mWs
Thermal resistance chip to heatsink per chip	R _{thJH}	Thermal grease thickness≤50µm						1,36		K/W
Thermal resistance chip to case per chip	R _{thJC}	λ=1W/mK						N/A		
Thermistor										
Rated resistance	R					T=25°C		1000		Ω
Deviation of R100	ΔR/R	R100=1670 Ω				T=100°C	-3		3	%
R100	P					T=100°C		1670,313		Ω
Power dissipation constant						T=25°C				mW/K
A-value	B(25/50)	Tol. %				T=25°C		7,635*10-3		1/K
B-value	B(25/100)	Tol. %				T=25°C		1,731*10-5		1/K²
Vincotech NTC Reference									E	

Output Inverter

Figure 1 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



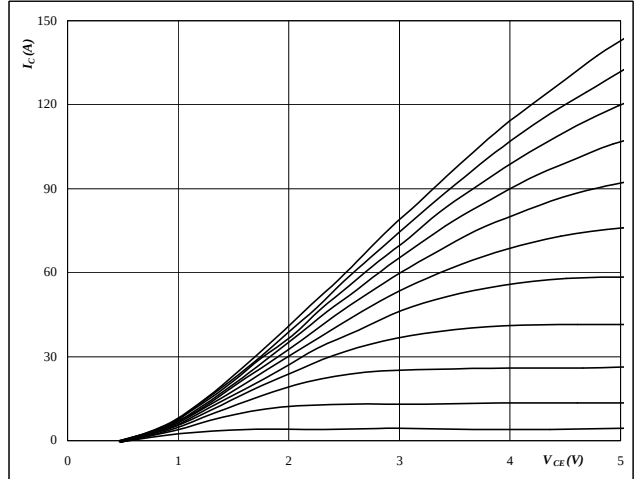
At

$t_p = 250 \mu s$
 $T_j = 25^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



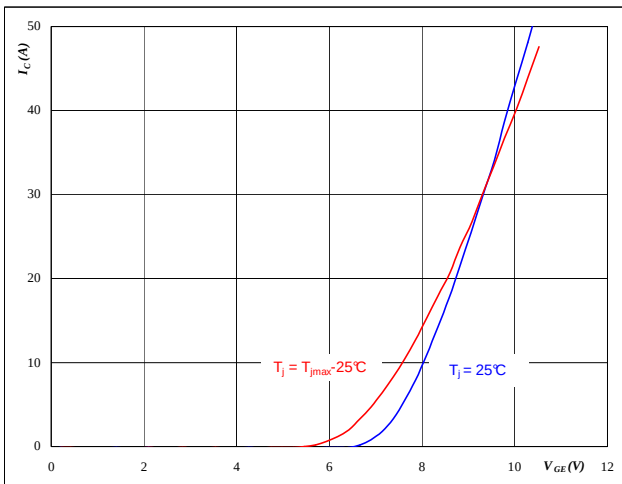
At

$t_p = 250 \mu s$
 $T_j = 150^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 Output inverter IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$



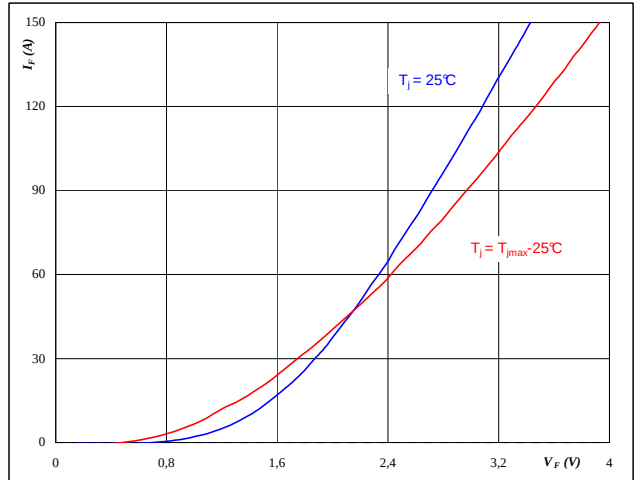
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4 Output inverter FRED

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



At

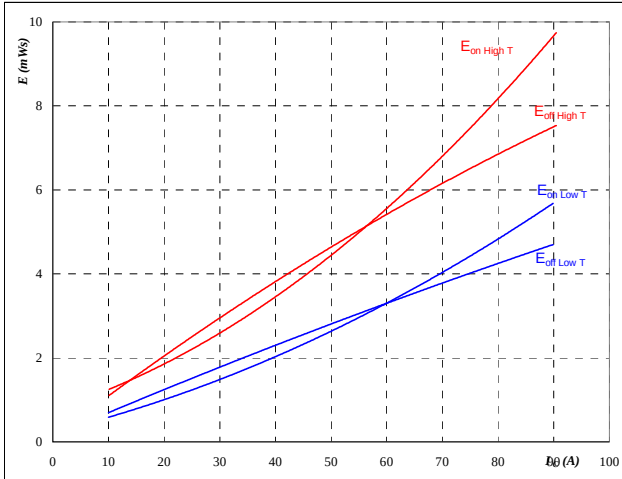
$t_p = 250 \mu s$

Output Inverter

Figure 5 Output inverter IGBT

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



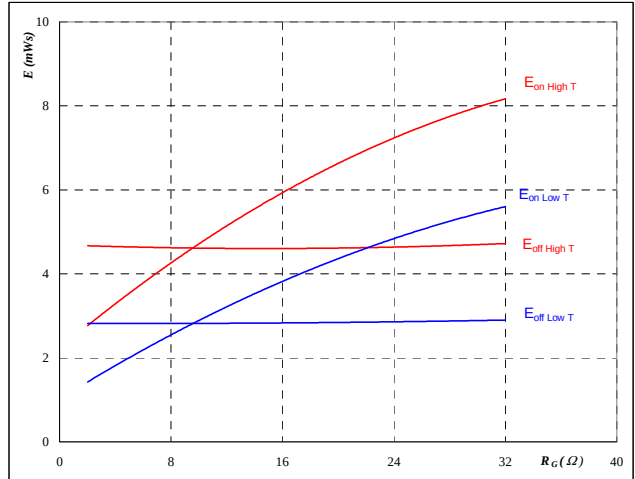
With an inductive load at

$T_J = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω
 $R_{goff} = 8$ Ω

Figure 6 Output inverter IGBT

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



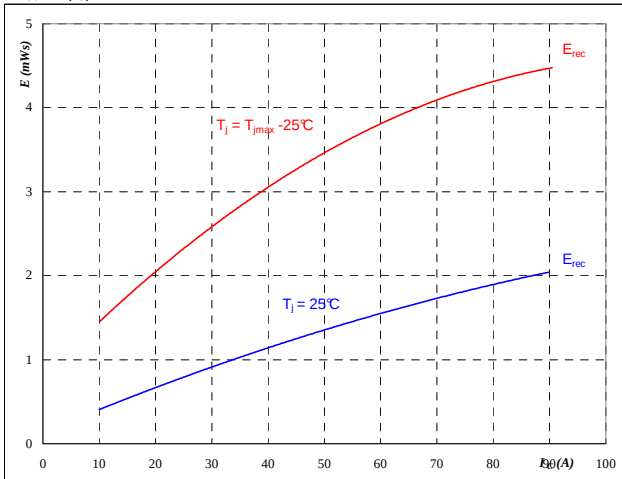
With an inductive load at

$T_J = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 50$ A

Figure 7 Output inverter IGBT

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



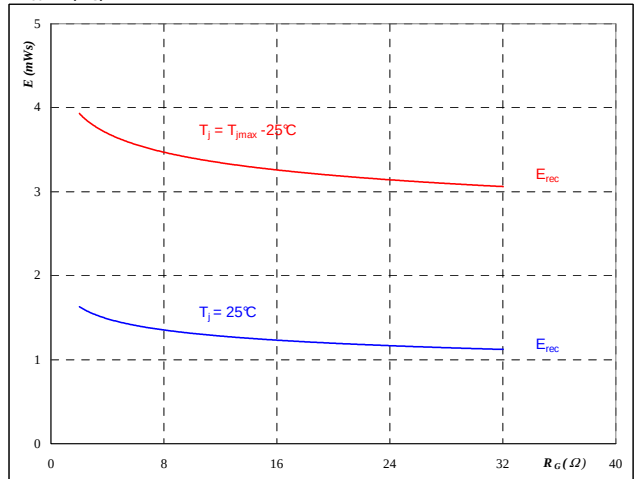
With an inductive load at

$T_J = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω

Figure 8 Output inverter IGBT

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

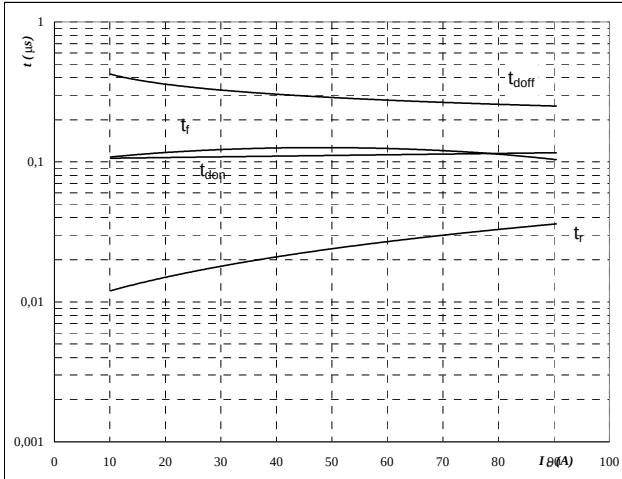
$T_J = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 50$ A

Output Inverter

Figure 9 Output inverter IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



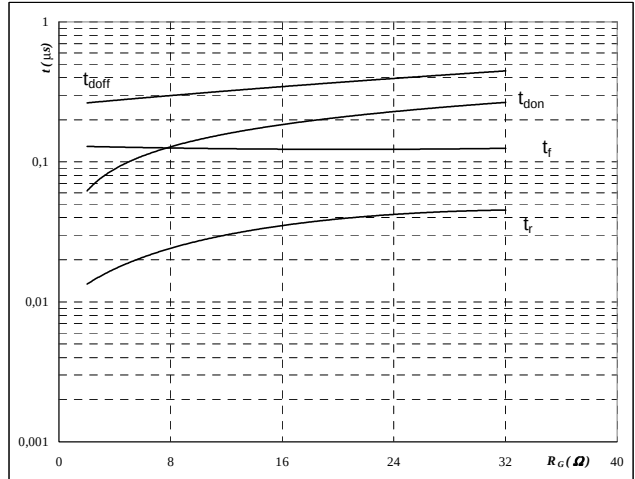
With an inductive load at

$T_J = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω
 $R_{goff} = 8$ Ω

Figure 10 Output inverter IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



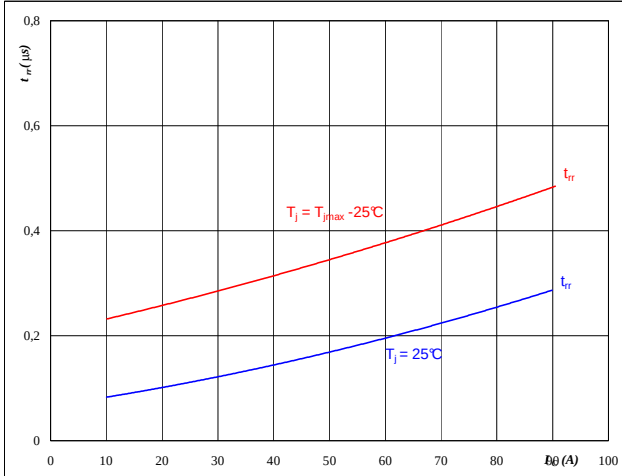
With an inductive load at

$T_J = 150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 50$ A

Figure 11 Output inverter FRED

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



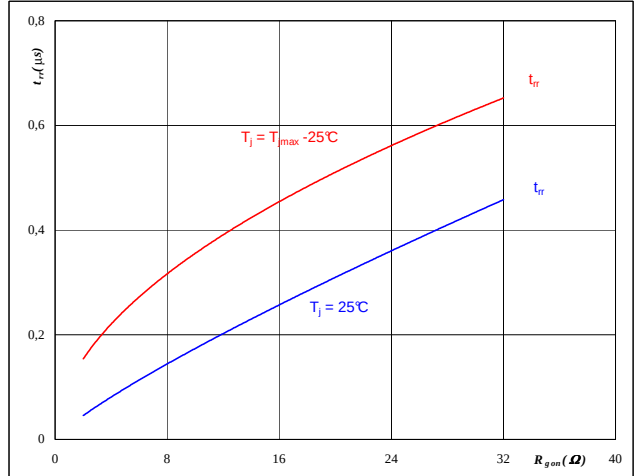
At

$T_J = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω

Figure 12 Output inverter FRED

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

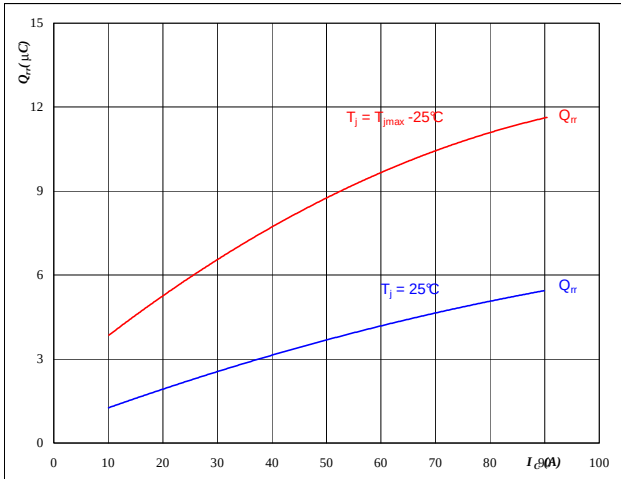
$T_J = 25/150$ °C
 $V_R = 600$ V
 $I_F = 50$ A
 $V_{GE} = \pm 15$ V

Output Inverter

Figure 13 Output inverter FRED

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$



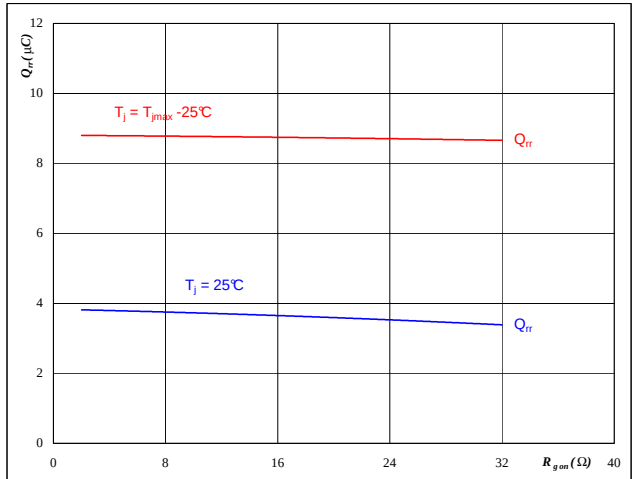
At

$T_j = 25/150^\circ\text{C}$
 $V_{CE} = 600\text{ V}$
 $V_{GE} = \pm 15\text{ V}$
 $R_{gon} = 8\ \Omega$

Figure 14 Output inverter FRED

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



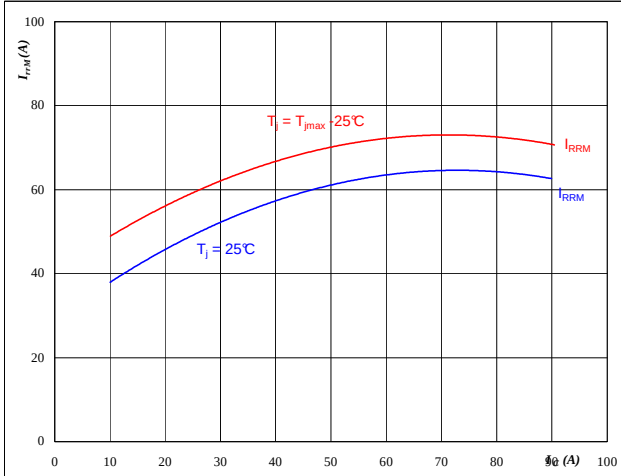
At

$T_j = 25/150^\circ\text{C}$
 $V_R = 600\text{ V}$
 $I_F = 50\text{ A}$
 $V_{GE} = \pm 15\text{ V}$

Figure 15 Output inverter FRED

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$



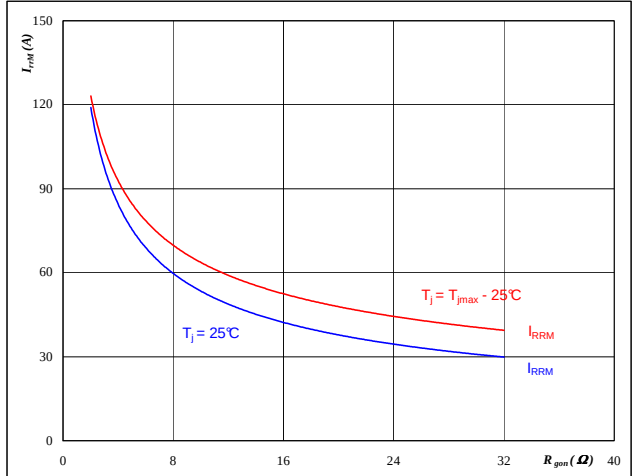
At

$T_j = 25/150^\circ\text{C}$
 $V_{CE} = 600\text{ V}$
 $V_{GE} = \pm 15\text{ V}$
 $R_{gon} = 8\ \Omega$

Figure 16 Output inverter FRED

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



At

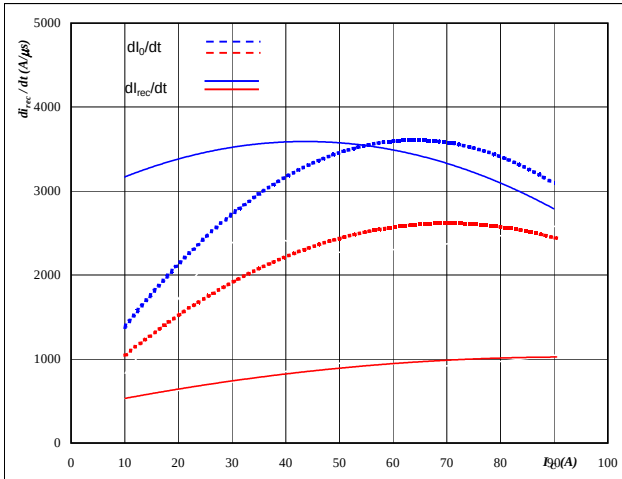
$T_j = 25/150^\circ\text{C}$
 $V_R = 600\text{ V}$
 $I_F = 50\text{ A}$
 $V_{GE} = \pm 15\text{ V}$

Output Inverter

Figure 17 Output inverter FRED

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$di_o/dt, di_{rec}/dt = f(I_C)$$



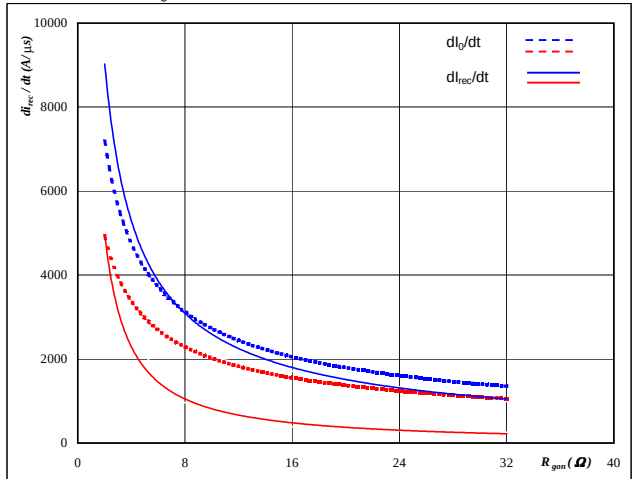
At

$T_j = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω

Figure 18 Output inverter FRED

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$di_o/dt, di_{rec}/dt = f(R_{gon})$$



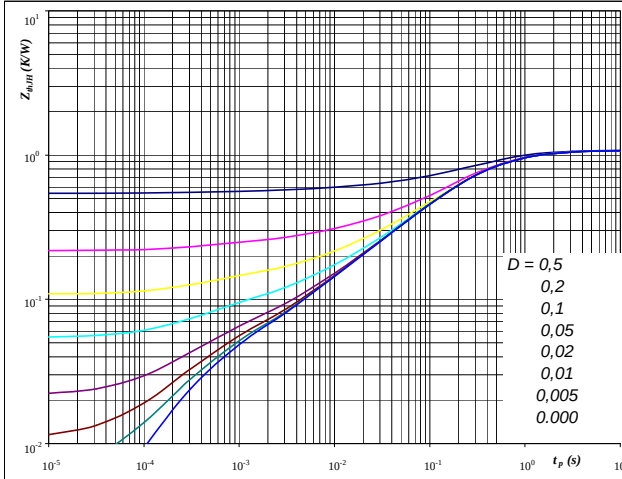
At

$T_j = 25/150$ °C
 $V_R = 600$ V
 $I_F = 50$ A
 $V_{GE} = \pm 15$ V

Figure 19 Output inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At

$D = t_p / T$
 $R_{thJH} = 1,09$ K/W

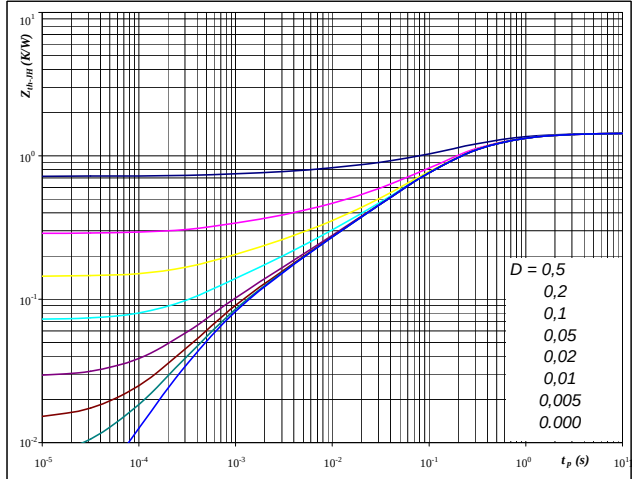
IGBT thermal model values

R (C/W)	Tau (s)
0,04	9,5E+00
0,23	1,0E+00
0,58	2,3E-01
0,15	3,4E-02
0,05	4,3E-03
0,03	4,0E-04

Figure 20 Output inverter FRED

FRED transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At

$D = t_p / T$
 $R_{thJH} = 1,44$ K/W

FRED thermal model values

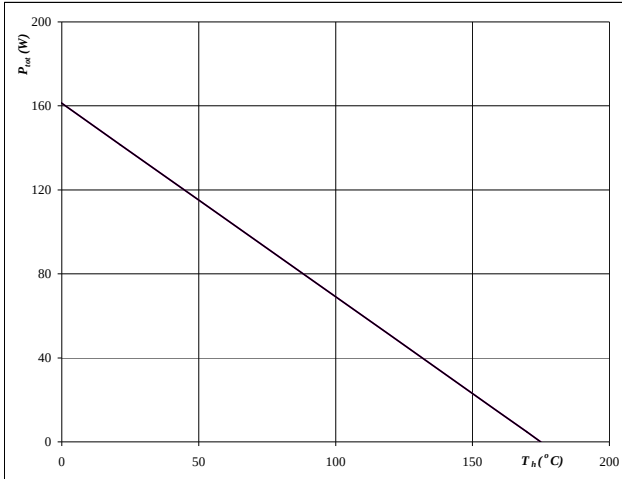
R (C/W)	Tau (s)
0,03	9,7E+00
0,26	9,0E-01
0,72	1,8E-01
0,27	3,1E-02
0,11	4,0E-03
0,05	5,8E-04

Output Inverter

Figure 21 Output inverter IGBT

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

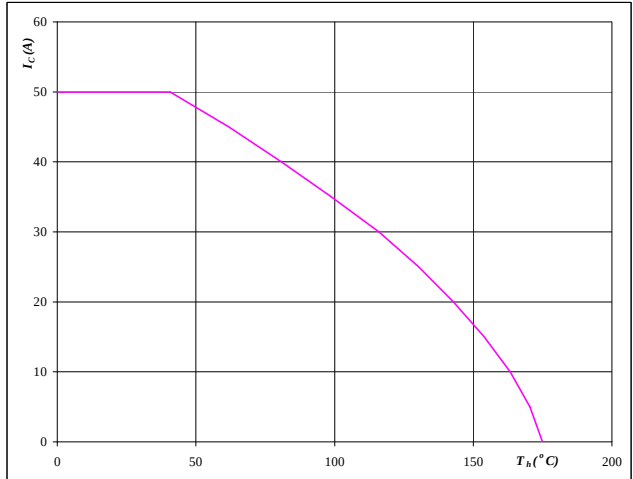


At
 $T_j = 175^{\circ}\text{C}$

Figure 22 Output inverter IGBT

Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$

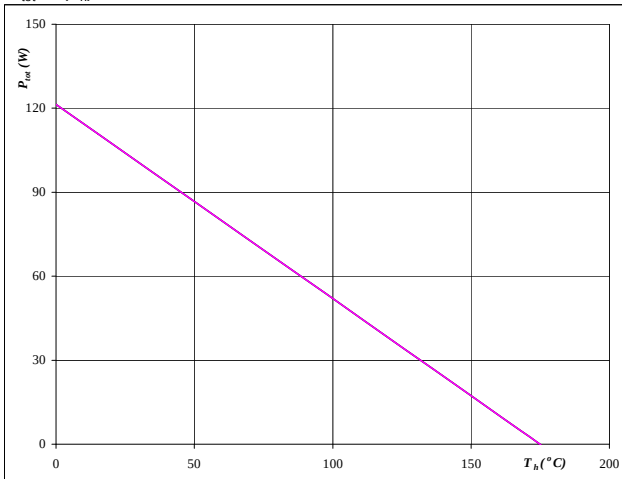


At
 $T_j = 175^{\circ}\text{C}$
 $V_{GE} = 15 \text{ V}$

Figure 23 Output inverter FRED

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

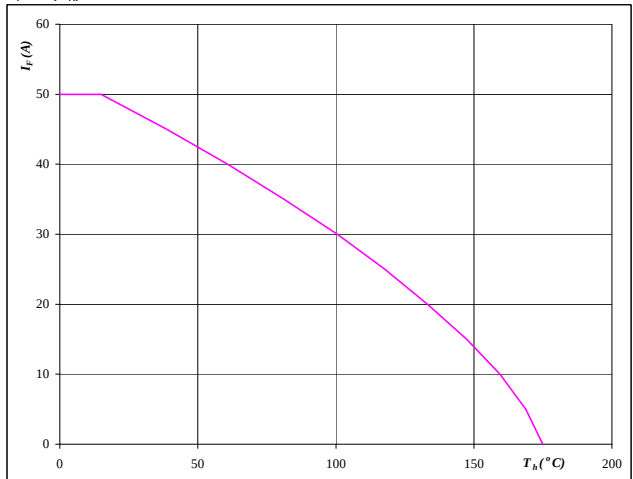


At
 $T_j = 175^{\circ}\text{C}$

Figure 24 Output inverter FRED

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$



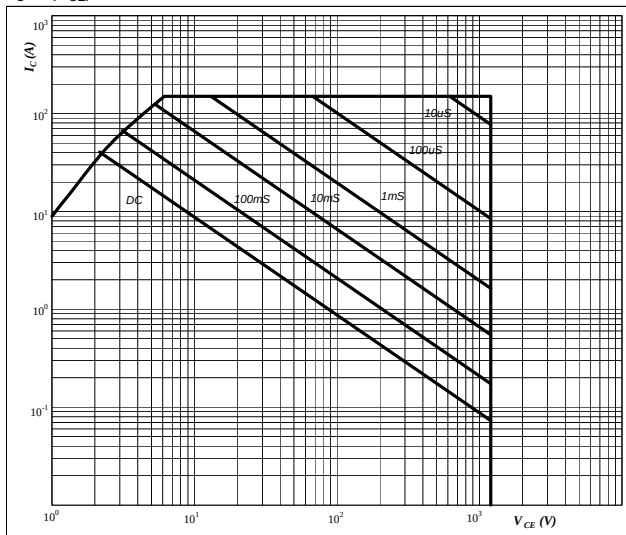
At
 $T_j = 175^{\circ}\text{C}$

Output Inverter

Figure 25 Output inverter IGBT

Safe operating area as a function
of collector-emitter voltage

$$I_C = f(V_{CE})$$



At

D = single pulse

$T_h = 80$ °C

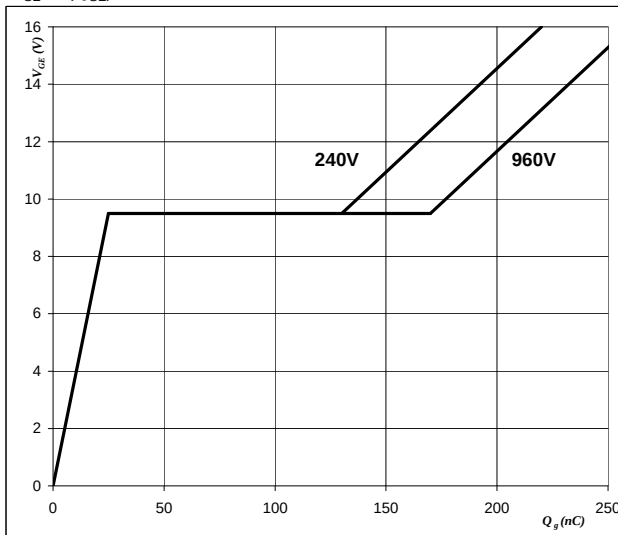
$V_{GE} = \pm 15$ V

$T_j = T_{jmax}$ °C

Figure 26 Output inverter IGBT

Gate voltage vs Gate charge

$$V_{GE} = f(Q_{GE})$$



At

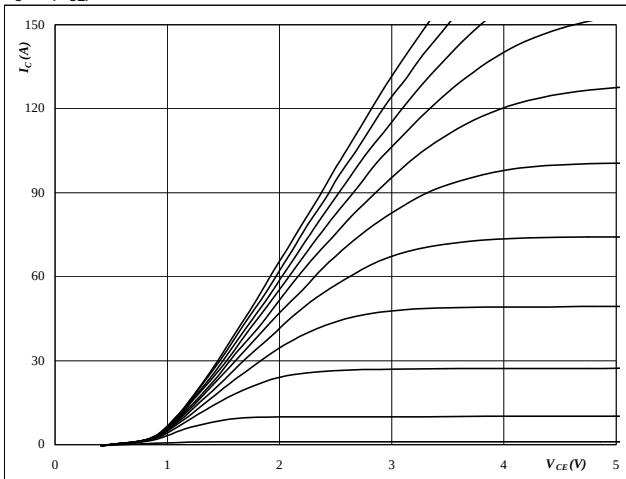
$I_C = 50$ A

Brake

Figure 1 Brake IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



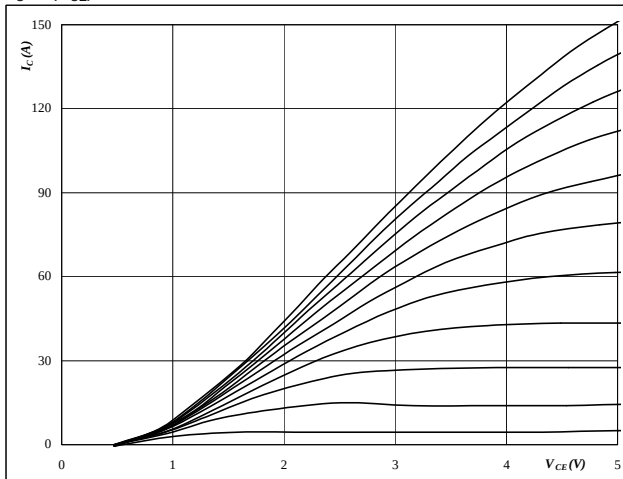
At

$t_p = 250 \mu s$
 $T_J = 25^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 Brake IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



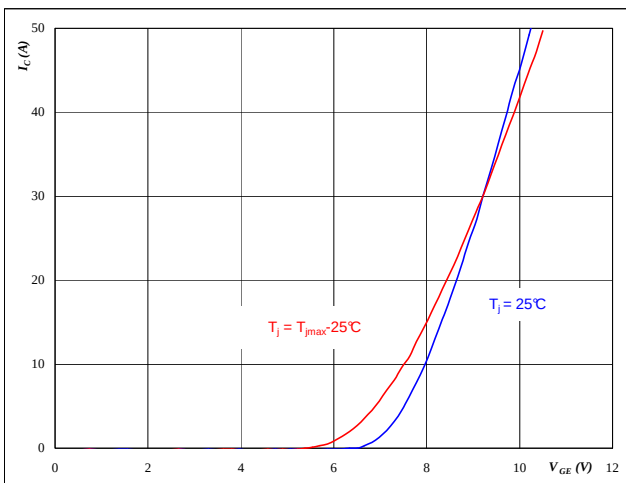
At

$t_p = 250 \mu s$
 $T_J = 150^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 Brake IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$



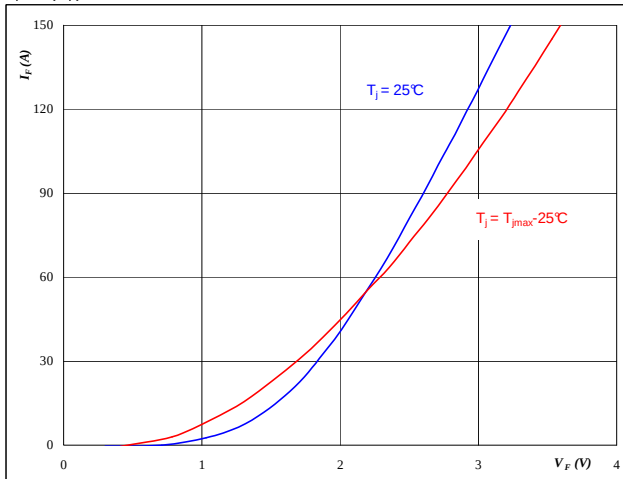
At

$t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4 Brake FRED

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



At

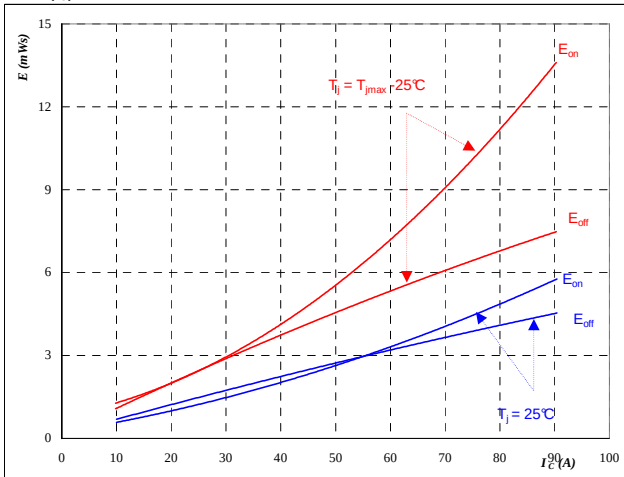
$t_p = 250 \mu s$

Brake

Figure 5 Brake IGBT

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



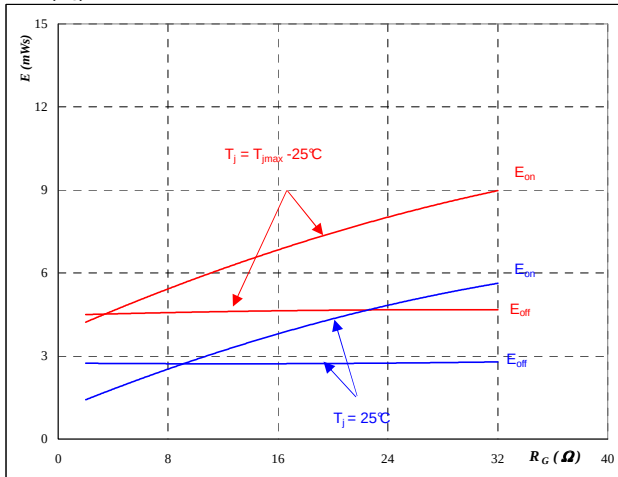
With an inductive load at

$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$
 $R_{goff} = 8 \text{ } \Omega$

Figure 6 Brake IGBT

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



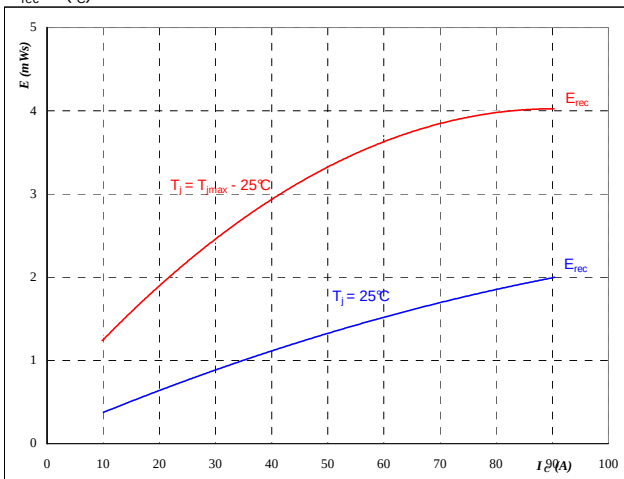
With an inductive load at

$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 50 \text{ A}$

Figure 7 Brake IGBT

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



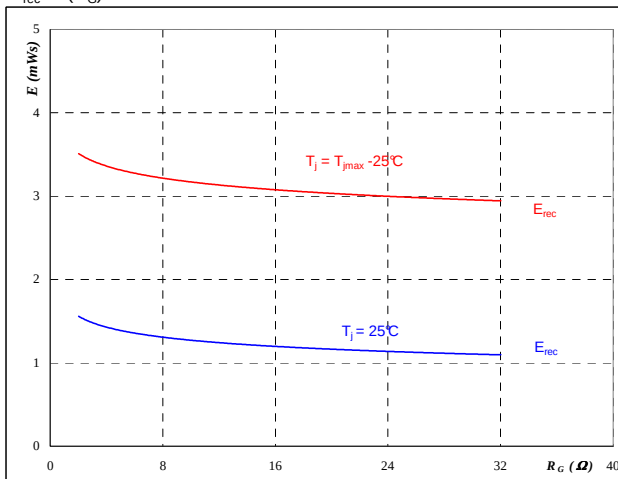
With an inductive load at

$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \text{ } \Omega$

Figure 8 Brake IGBT

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

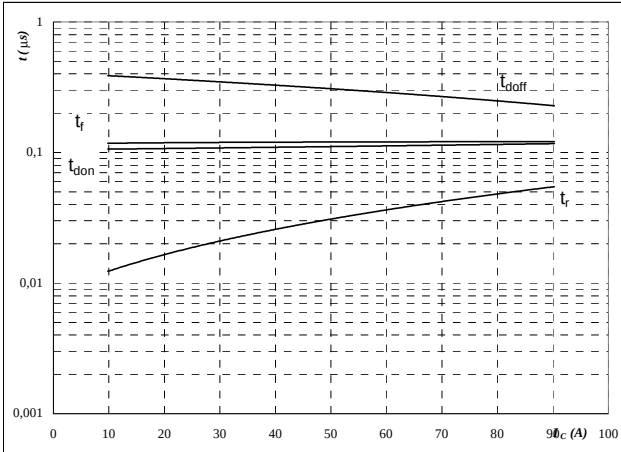
$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 50 \text{ A}$

Brake

Figure 9 Brake IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



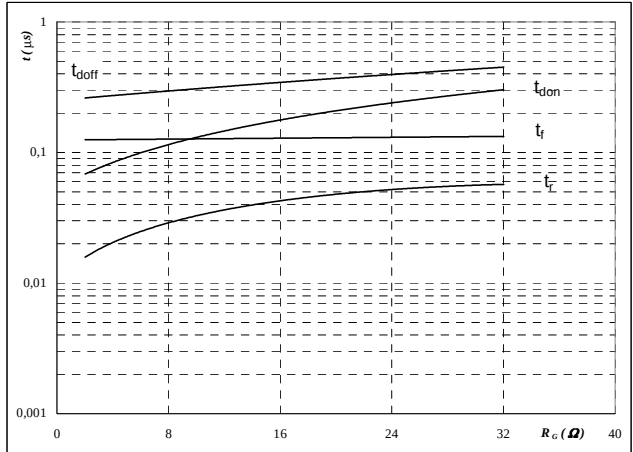
With an inductive load at

$T_J = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 8$ Ω
 $R_{goff} = 8$ Ω

Figure 10 Brake IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



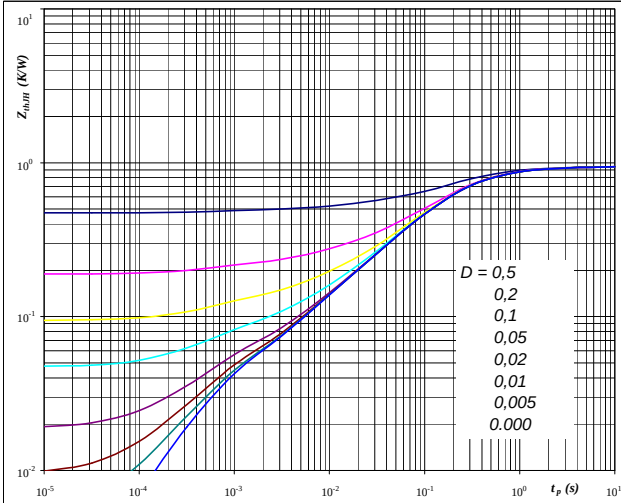
With an inductive load at

$T_J = 25/150$ °C
 $V_{CE} = 600$ V
 $V_{GE} = \pm 15$ V
 $I_C = 50$ A

Figure 11 Brake IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



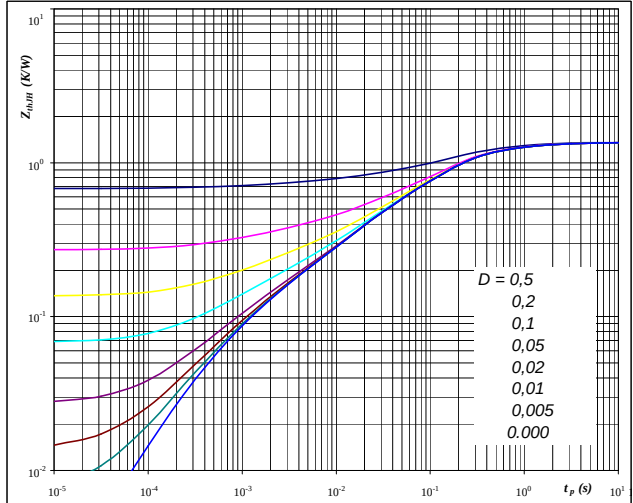
At

$D = t_p / T$
 $R_{thJH} = 0.94$ K/W

Figure 12 Brake FRED

FRED transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At

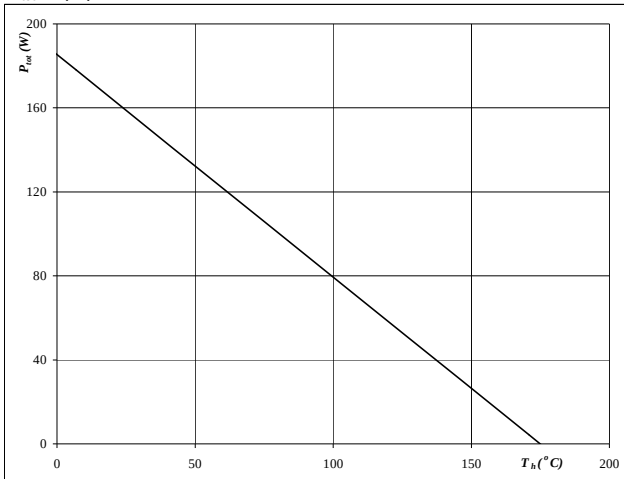
$D = t_p / T$
 $R_{thJH} = 1.36$ K/W

Brake

Figure 13 Brake IGBT

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

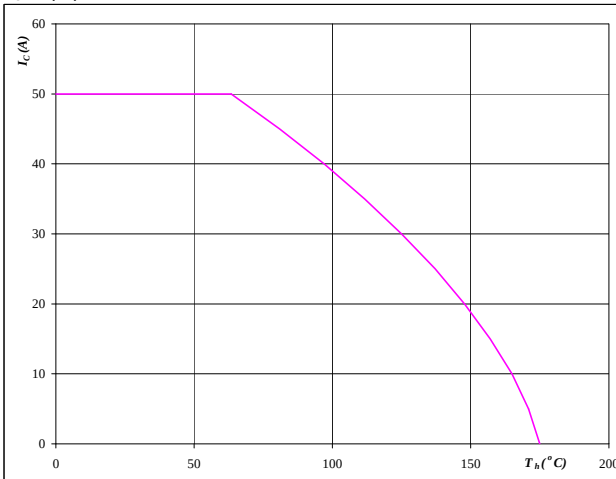


At
 $T_j = 175$ °C

Figure 14 Brake IGBT

Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$

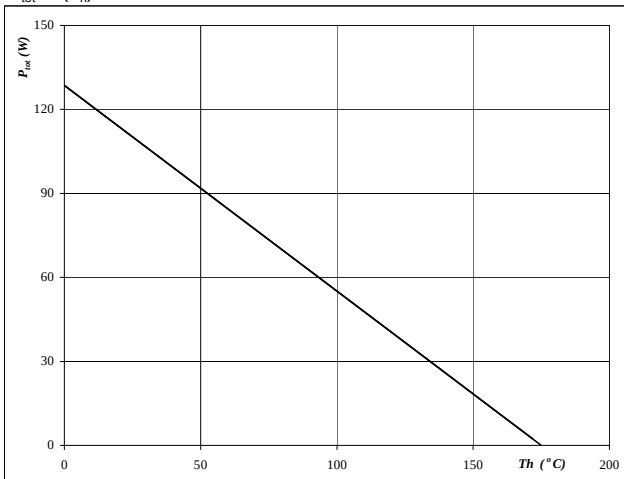


At
 $T_j = 175$ °C
 $V_{GE} = 15$ V

Figure 15 Brake FRED

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

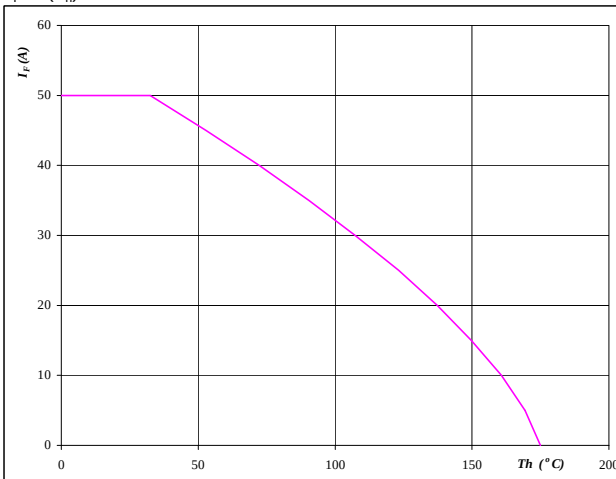


At
 $T_j = 175$ °C

Figure 16 Brake FRED

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$



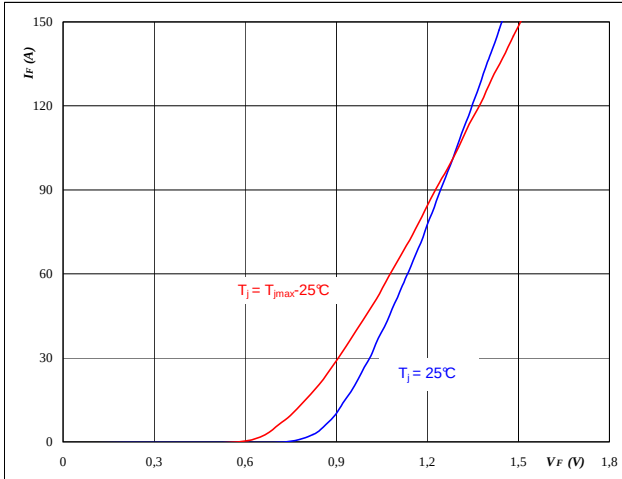
At
 $T_j = 175$ °C

Input Rectifier Bridge

Figure 1 Rectifier diode

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$

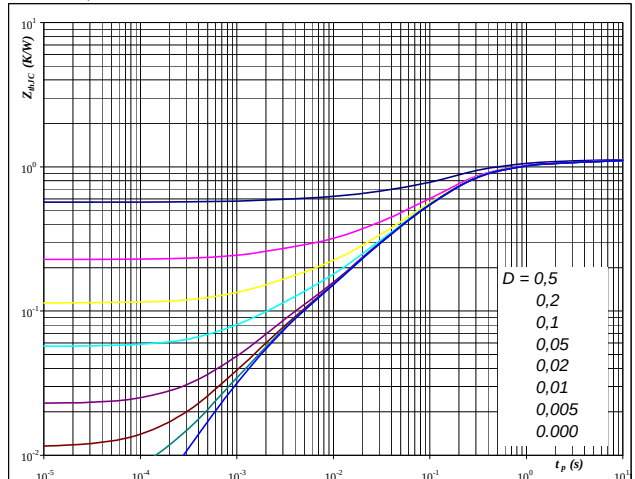


At
 $t_p = 250 \mu s$

Figure 2 Rectifier diode

Diode transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$

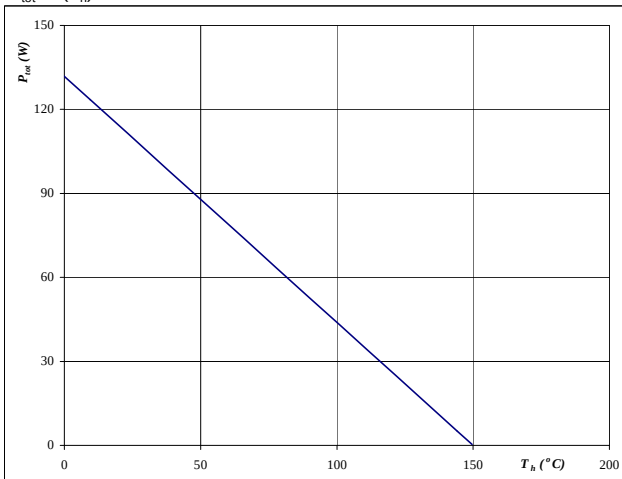


At
 $D = t_p / T$
 $R_{thJH} = 1,138 \text{ K/W}$

Figure 3 Rectifier diode

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

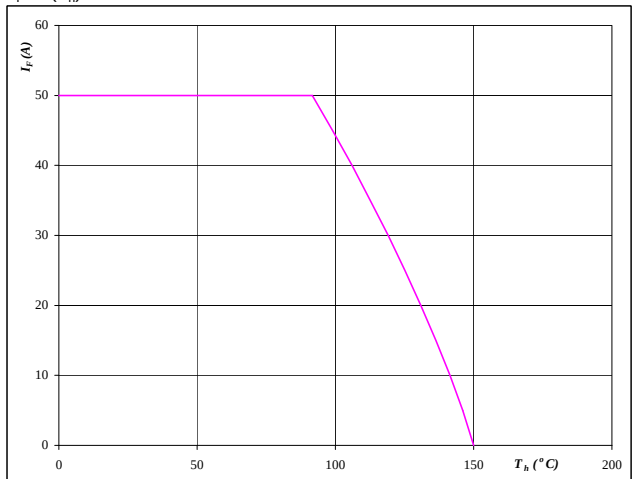


At
 $T_j = 150 \text{ °C}$

Figure 4 Rectifier diode

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$



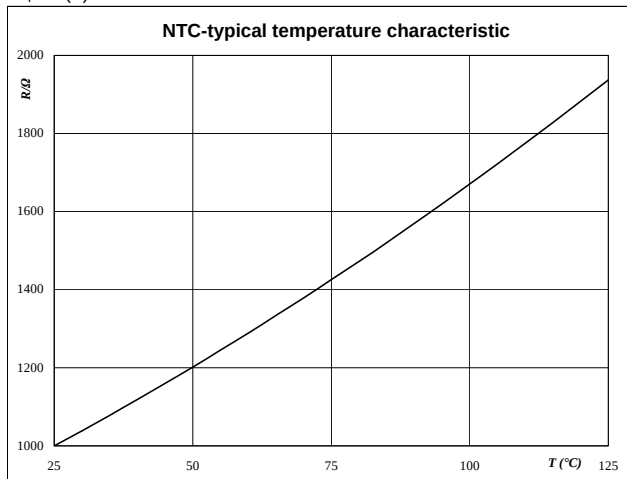
At
 $T_j = 150 \text{ °C}$

Thermistor

Figure 1 Thermistor

Typical NTC characteristic
as a function of temperature

$$R_T = f(T)$$



Switching Definitions Output Inverter

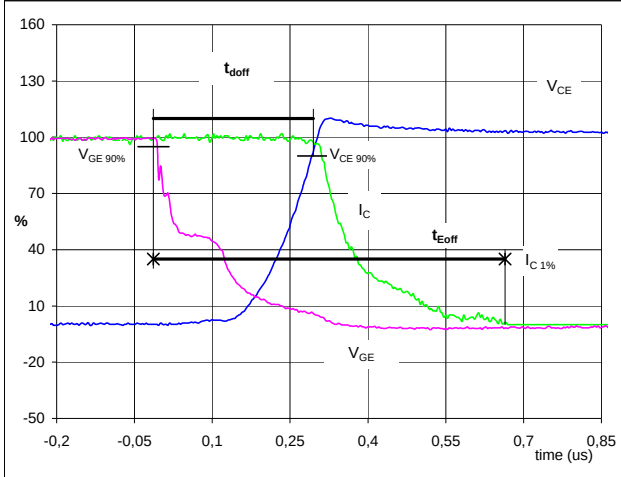
General conditions

T_j	=	150 °C
R_{gon}	=	8 Ω
R_{goff}	=	8 Ω

Figure 1 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}

(t_{Eoff} = integrating time for E_{off})

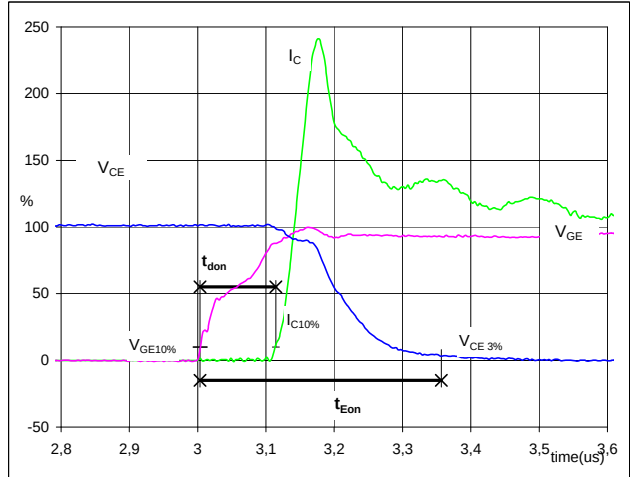


$V_{GE}(0\%)$	=	-15	V
$V_{GE}(100\%)$	=	15	V
$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	50	A
t_{doff}	=	0,30	μs
t_{Eoff}	=	0,68	μs

Figure 2 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}

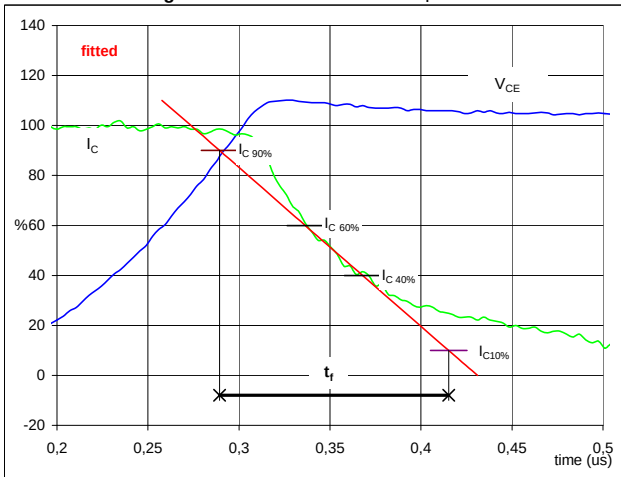
(t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$	=	-15	V
$V_{GE}(100\%)$	=	15	V
$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	50	A
t_{don}	=	0,11	μs
t_{Eon}	=	0,35	μs

Figure 3 Output inverter IGBT

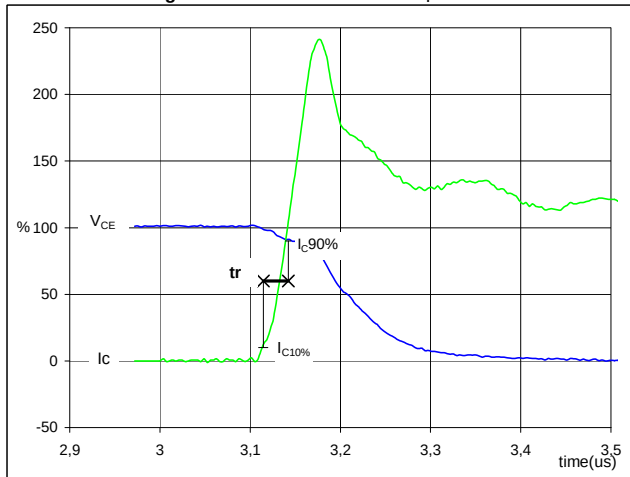
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	50	A
t_f	=	0,13	μs

Figure 4 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_r

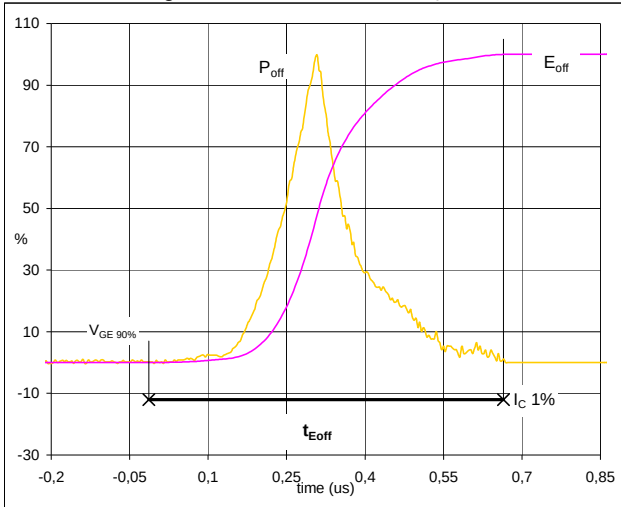


$V_C(100\%)$	=	600	V
$I_C(100\%)$	=	50	A
t_r	=	0,03	μs

Switching Definitions Output Inverter

Figure 5 Output inverter IGBT

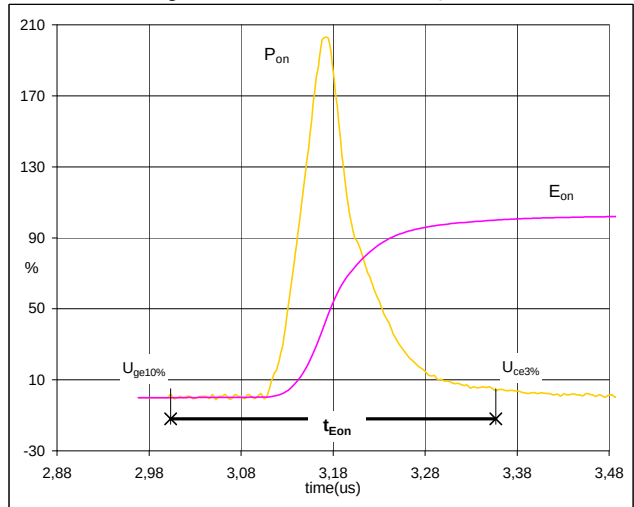
Turn-off Switching Waveforms & definition of t_{Eoff}



$P_{off}(100\%) = 29,95$ kW
 $E_{off}(100\%) = 4,58$ mJ
 $t_{Eoff} = 0,68$ μ s

Figure 6 Output inverter IGBT

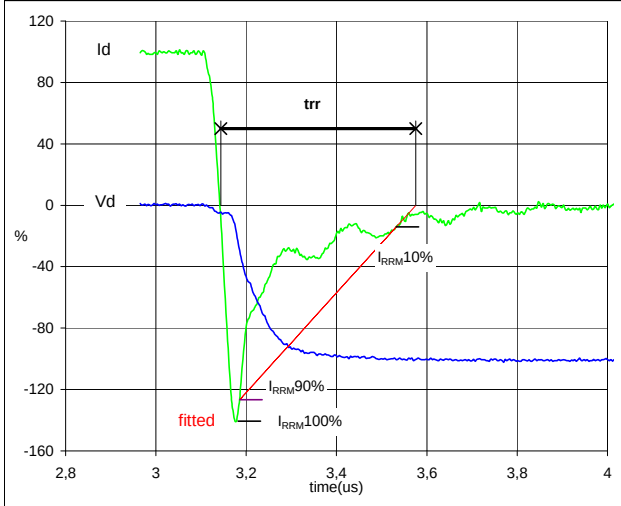
Turn-on Switching Waveforms & definition of t_{Eon}



$P_{on}(100\%) = 29,95$ kW
 $E_{on}(100\%) = 4,46$ mJ
 $t_{Eon} = 0,35$ μ s

Figure 78 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{tr}

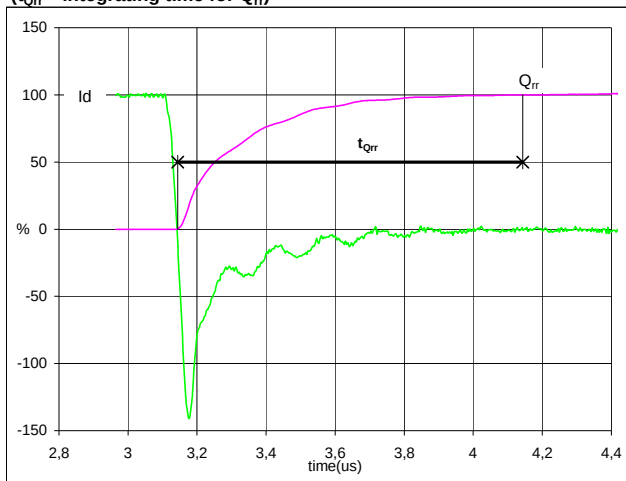


$V_d(100\%) = 600$ V
 $I_d(100\%) = 50$ A
 $I_{RRM}(100\%) = -71$ A
 $t_{tr} = 0,31$ μ s

Switching Definitions Output Inverter

Figure 8 Output inverter FRED

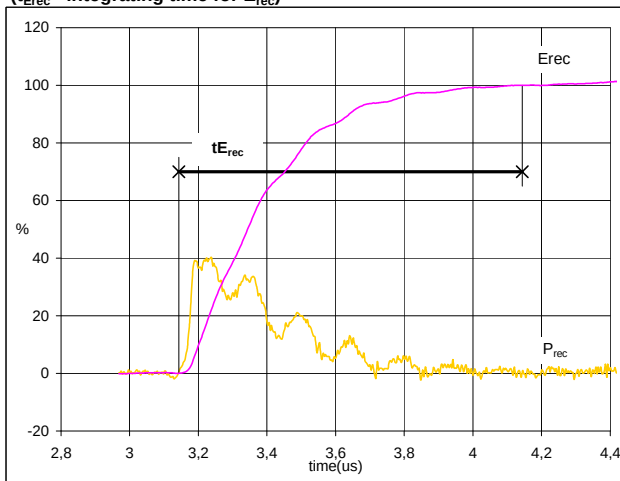
Turn-on Switching Waveforms & definition of t_{Qrr}
(t_{Qrr} = integrating time for Q_{rr})



I_d (100%) = 50 A
 Q_{rr} (100%) = 8,80 μC
 t_{Qrr} = 1,00 μs

Figure 9 Output inverter FRED

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec} = integrating time for E_{rec})



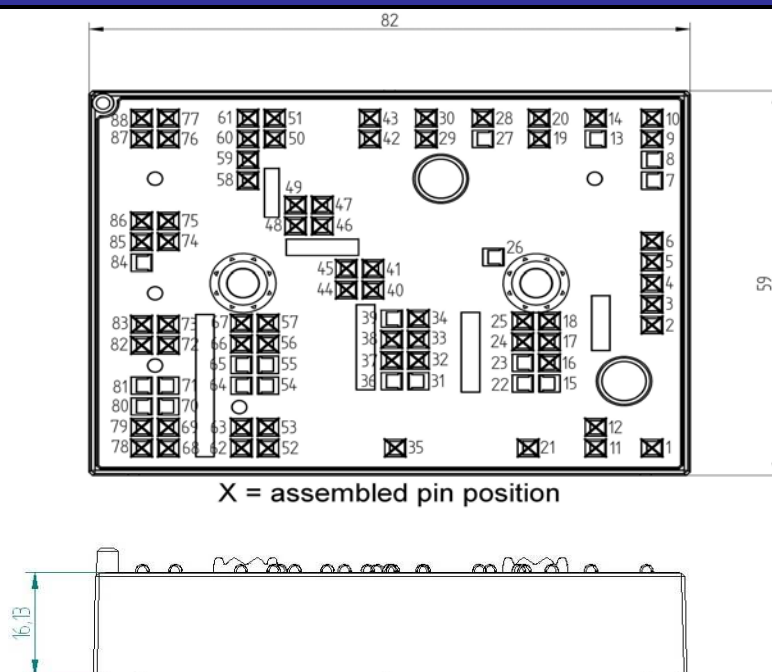
P_{rec} (100%) = 29,95 kW
 E_{rec} (100%) = 3,48 mJ
 t_{Erec} = 1,00 μs

Ordering Code and Marking - Outline - Pinout

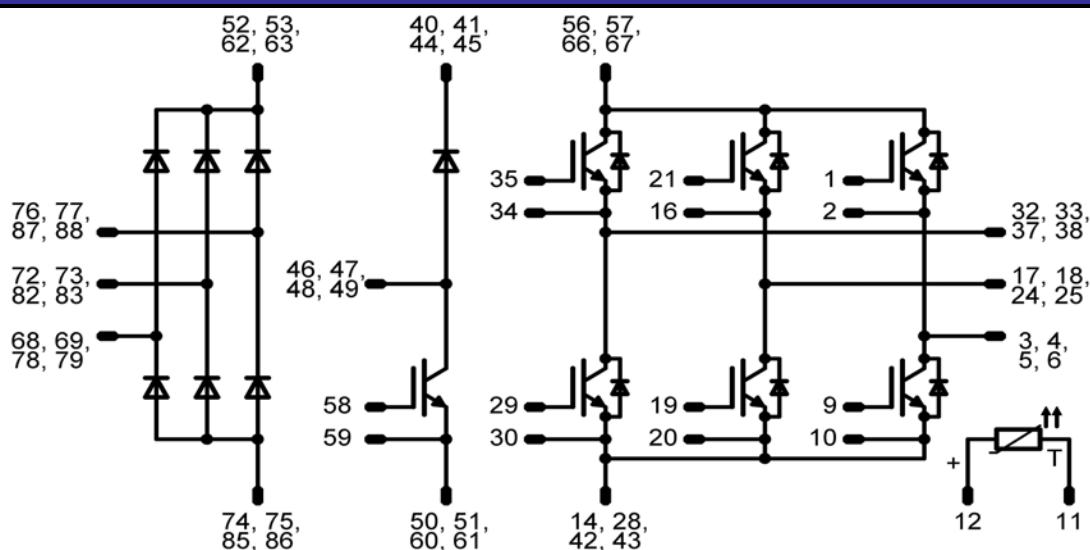
Ordering Code & Marking

Version	Ordering Code	in DataMatrix as	in packaging barcode as
with std lid (black V23990-K12-T-PM)	V23990-K428-A40-/0A/-PM	K428A40	K428A40-/0A/
with std lid (black V23990-K12-T-PM) and P12	V23990-K428-A40-/1A/-PM	K428A40	K428A40-/1A/
with thin lid (white V23990-K13-T-PM)	V23990-K428-A40-/0B/-PM	K428A40	K428A40-/0B/
with thin lid (white V23990-K13-T-PM) and P12	V23990-K428-A40-/1B/-PM	K428A40	K428A40-/1B/

Outline



Pinout



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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.